

## Product Change Notification - KSRA-07LZOY150

**Date:** 22 Sep 2017  
**Product Category:** Digital Potentiometers; 8-bit PIC Microcontrollers  
**Notification subject:** CCB 3082 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 160K wafer technology available in 16L QFN package at NSEB assembly site  
**Notification text:** **PCN Status:**  
Initial notification

**Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond in selected products of the 160K wafer technology available in 16L QFN package at NSEB assembly site

**Pre Change:**

Using gold (Au) bond wire and EFTEC-64T lead frame material

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire and C194 lead frame material

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	NSEB Assembly Site	NSEB Assembly Site
<b>Wire material</b>	Au Wire	CuPdAu Wire
<b>Die attach material</b>	8600	8600
<b>Molding compound material</b>	G700LTD	G700LTD
<b>Lead frame material</b>	EFTEC-64T	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated Qualification Completion Date:**

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Time Table Summary:**

Workweek	September 2017					-->	January 2018				
	35	36	37	38	39		01	02	03	04	05
Initial PCN Issue Date				X							
Qual Report Availability							X				
Final PCN Issue Date							X				

**Method to Identify Change:**

Traceability code

**Qualification Plan:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Plan

**Revision History:**

**September 22, 2017:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

- [PCN\\_KSRA-07LZOY150\\_Affected CPN.pdf](#)
- [PCN\\_KSRA-07LZOY150\\_Qual Plan.pdf](#)
- [PCN\\_KSRA-07LZOY150\\_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

<b>PCN_KSRA-07LZOY150</b>
<b>CATALOG_PART_NBR</b>
MCP4231-103E/ML
MCP4231-104E/ML
MCP4231-502E/ML
MCP4231-503E/ML
MCP4231T-103E/ML
MCP4231T-104E/ML
MCP4231T-502E/ML
MCP4231T-503E/ML
MCP4241-103E/ML
MCP4241-104E/ML
MCP4241-502E/ML
MCP4241-503E/ML
MCP4241T-103E/ML
MCP4241T-104E/ML
MCP4241T-502E/ML
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MCP4261-103E/ML
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MCP4631T-103E/ML
MCP4631T-104E/ML
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MCP4631T-503E/ML
MCP4641T-103E/ML
MCP4641T-104E/ML
MCP4641T-502E/ML
MCP4641T-503E/ML
MCP4651T-103E/ML
MCP4651T-104E/ML
MCP4651T-502E/ML

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<b>PCN_KSRA-07LZOY150</b>
<b>CATALOG_PART_NBR</b>
MCP4651T-503E/ML
MCP4661T-103E/ML
MCP4661T-104E/ML
MCP4661T-104QE/ML
MCP4661T-502E/ML
MCP4661T-503E/ML
MCP4661T-503QE/ML
PIC16F610-E/ML
PIC16F610-I/ML
PIC16F610T-E/ML
PIC16F610T-I/ML
PIC16F616-E/ML
PIC16F616-H/ML
PIC16F616-I/ML
PIC16F616T-E/ML
PIC16F616T-E/MLC07
PIC16F616T-I/ML
PIC16F616T-I/ML034
PIC16F616T-I/ML042
PIC16F616T-I/ML066
PIC16F636-I/ML
PIC16F636T-I/ML
PIC16F636T-I/ML037
PIC16F684-E/ML
PIC16F684-I/ML
PIC16F684T-I/ML
PIC16F684T-I/ML065
PIC16F684T-I/ML070
PIC16F688-E/ML
PIC16F688-I/ML
PIC16F688T-I/ML
PIC16F688T-I/MLAPL
PIC16F753-E/ML
PIC16F753-I/ML
PIC16F753T-I/ML
PIC16HV610-E/ML
PIC16HV610-I/ML
PIC16HV610T-I/ML
PIC16HV616-E/ML
PIC16HV616-I/ML
PIC16HV616T-E/ML
PIC16HV616T-I/ML
PIC16HV753-E/ML

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<b>PCN_KSRA-07LZOY150</b>
<b>CATALOG_PART_NBR</b>
PIC16HV753-I/ML
PIC16HV753T-I/ML